



## Material Content Data Sheet



Sales Product Name	ESD8V0L1B-02LRH E6327			Issued		29. August 2013		
MA#	MA000456700							
Package	PG-TSLP-2-17			Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.15		1492	
	noble metal	gold	7440-57-5	0.004	0.58		5785	
	inorganic material	silicon	7440-21-3	0.043	7.06	7.79	70608	77885
leadframe	non noble metal	nickel	7440-02-0	0.138	22.72	22.72	227156	227156
wire	noble metal	gold	7440-57-5	0.005	0.82	0.82	8181	8181
encapsulation	organic material	carbon black	1333-86-4	0.004	0.64		6449	
	plastics	epoxy resin	-	0.053	8.71		87076	
	inorganic material	silicondioxide	60676-86-0	0.335	55.14	64.49	551483	645008
leadfinish	noble metal	gold	7440-57-5	0.010	1.59	1.59	15864	15864
plating	noble metal	silver	7440-22-4	0.016	2.59	2.59	25906	25906
*deviation	< 10%	Sum in total:				100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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